

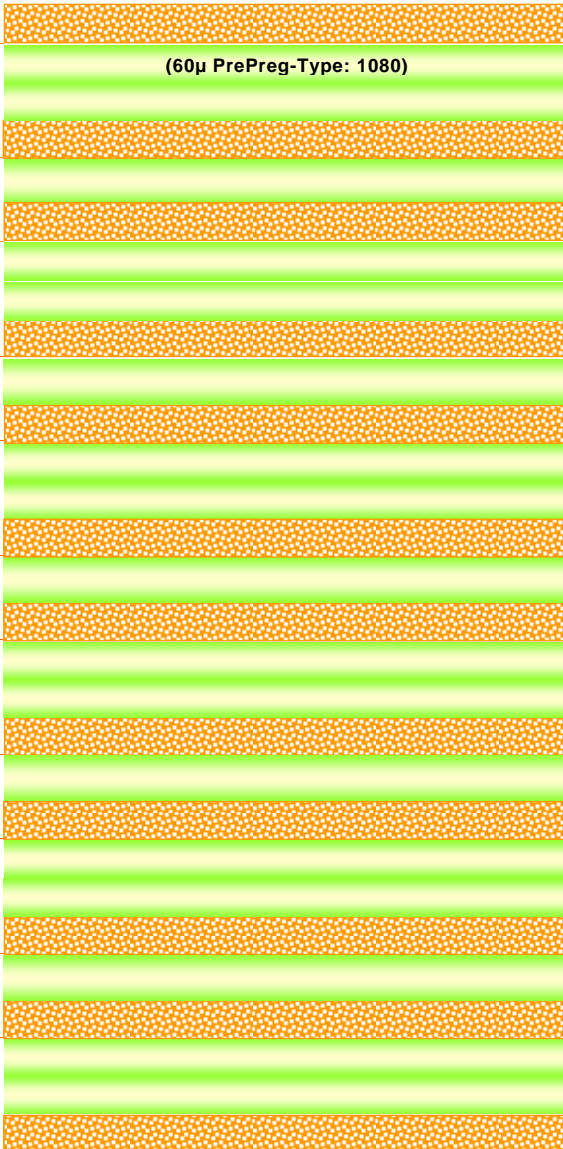
Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
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12 189 FR4 35 L15.35 P06

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

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Layers	in μ	Material	Build-Up	Assembly	
Layer-1	35 μ	Copper		B	
	60 μ	Prepreg			
Layer-2	60 μ	Prepreg			A1
	35 μ	Copper			
Layer-3	150 μ	L-FR4			A2
	35 μ	Copper			
Layer-4	60 μ	Prepreg			A3
	60 μ	Prepreg			
Layer-5	35 μ	Copper			A4
	150 μ	L-FR4			
Layer-6	35 μ	Copper			A5
	60 μ	Prepreg			
Layer-7	60 μ	Prepreg	A5		
	35 μ	Copper			
Layer-8	150 μ	L-FR4	A5		
	35 μ	Copper			
Layer-9	60 μ	Prepreg	A5		
	60 μ	Prepreg			
Layer-10	35 μ	Copper	A5		
	150 μ	L-FR4			
Layer-11	35 μ	Copper	A5		
	60 μ	Prepreg			
Layer-99	60 μ	Prepreg	A5		
	35 μ	Copper			

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